Abstract

Method for the application of multiple discrete layer fragments made of dried metal sintering preparation to pre-determined electrically-conductive surface fractions of a substrate for electronic components, comprising the steps of:

(1) applying multiple discrete layer fragments made of metal sintering preparation to one side of a planar transfer substrate in an arrangement that is mirror-symmetrical to the pre-determined electrically-conductive surface fractions;

(2) drying the metal sintering preparation thus applied while preventing sintering;

(3) arranging and contacting the transfer substrate with the layer fragments made of dried metal sintering preparation such as to face the surface of the substrate for electronic components and, while assuring coincident positioning of the surface fractions of the transfer substrate provided with the dried metal sintering preparation and the pre-determined electrically-conductive surface fractions of the substrate for electronic components;

(4) applying compressive force to the contact arrangement produced in step (3); and

(5) removing the transfer substrate from the contact arrangement;

whereby the adhesive force of the dried metal sintering preparation with respect to the pre-determined electrically-conductive surface fractions of the substrate for electronic components after completion of step (4) is larger than the adhesive force with respect to the surface of the transfer substrate;

whereby the planar transfer substrate is a non-sinterable and, if applicable, coated metal foil or a thermoplastic film;

whereby the substrate for electronic components is a substrate having a planar surface comprising one or more depressions of 10 to 500 µm and, in addition, is selected from the group consisting of leadframes, ceramic substrates, DCB substrates, and metal composite materials, and whereby at least one pre-determined electrically-conductive surface fraction is situated in a depression.